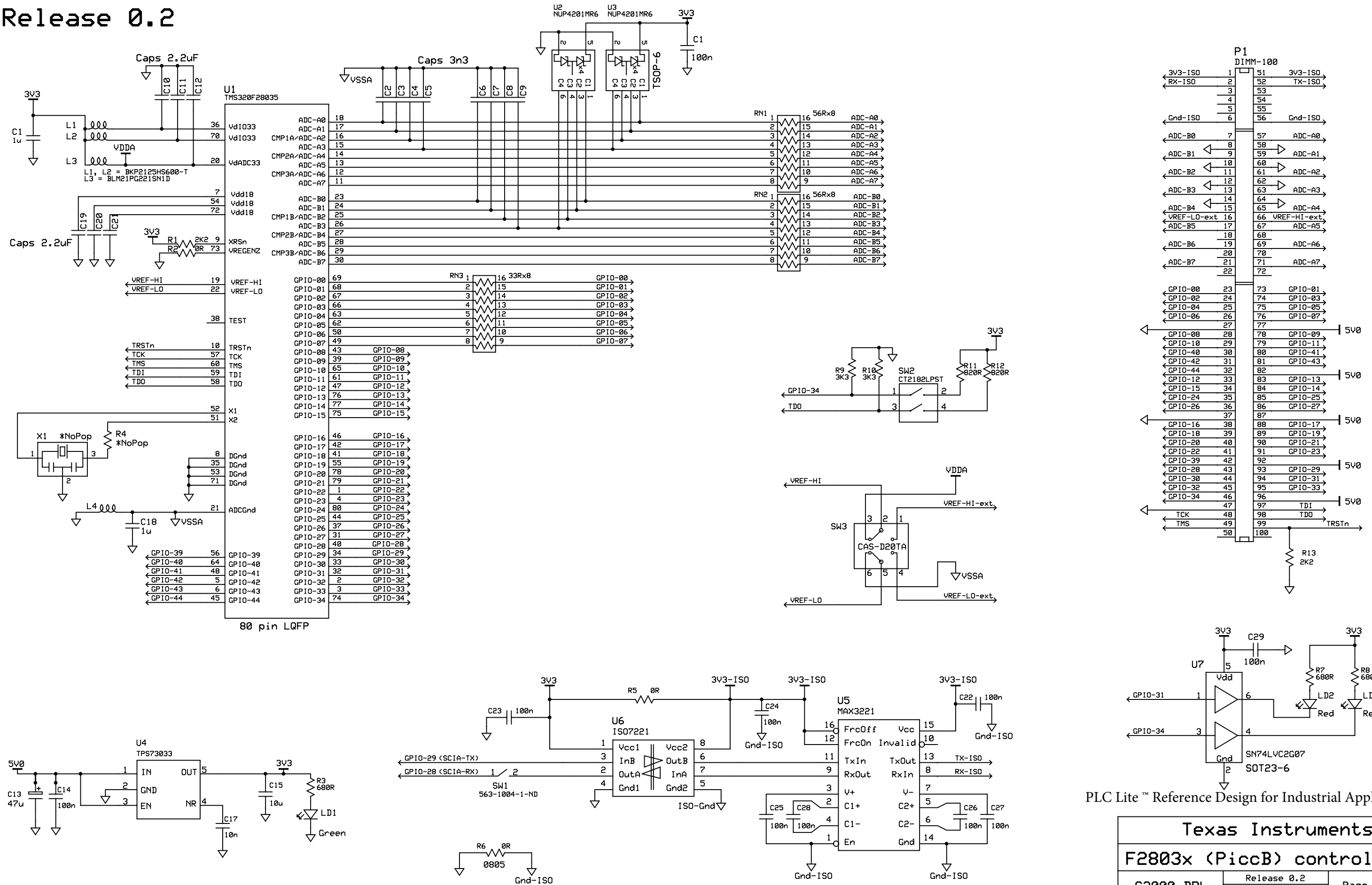


Release 0.2



Revision Notes:

- V2 - Release 1 "A"
1. First Release (R1)
- V2- Release 2 "B"
1. Updated part C12
 2. Added R5 & C11 to TXRX line
 3. Added PI filter to 12V input (L1,C7,C6)
 4. Added PI filter to 5V PTH output (L2,C8,C9)
 5. Added R6 to TRDRVEn
 6. Added J10 for 2nd AFE rev

- V2- Release 3 "C"
1. Added J11/J12 to select USB or ISO for SCIB ISO for SCIC
 2. Added J13/J14/J15/J16 to select McBSP-B or SPI-A
 3. Removed TX/RX - slave from GPIO-29/28
 - 4.LED Circuit
Added LEDs Circuit LD3-8
Added U5
Added R7,8,10,11,12,17
Added C10
Connected GP ?,?,?,?,?
 5. Removed Bright LED Circuit
 6. Changed TB1 Part
 7. removed J5, J7, J9, C12
 8. updated components C11, C9, C5, and C6

- V3- Release 1 "D"
1. Moved TXDRVN to GP12
 2. Moved GP33 to PG30, GP31 to GP28
 3. Added I2C nets GP33/32, I2C EEPROMS, and discretes
 4. Added ZeroCross Circuit and connected to GP05
 5. Added T2 Xfmr
 6. Changed C13 Value
 7. Added L3/L4
 8. Added Boot Options GP84/85

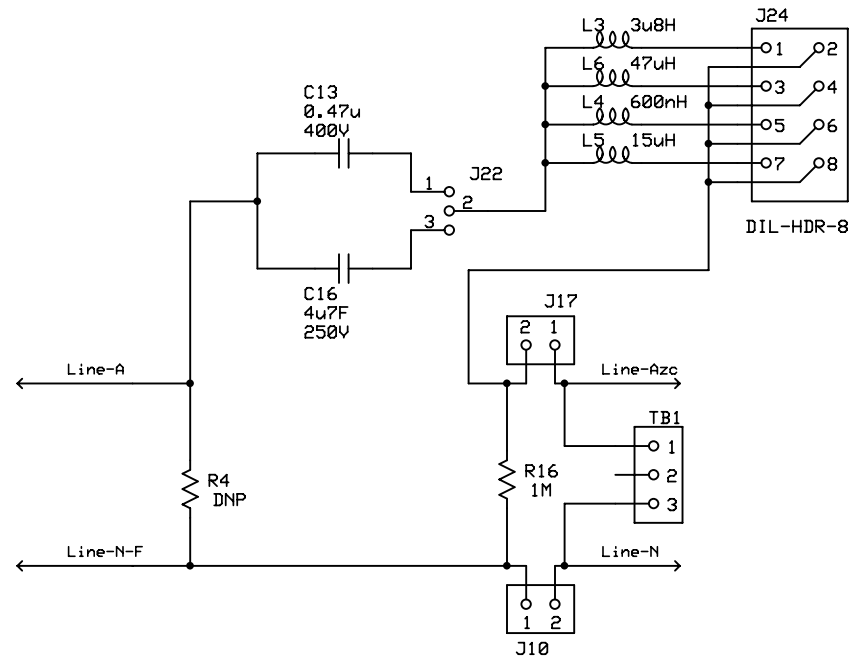
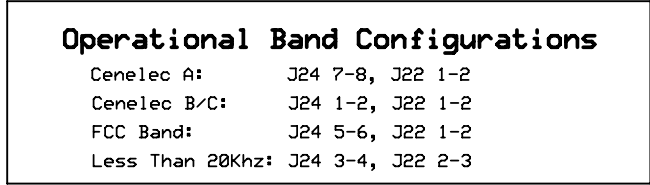
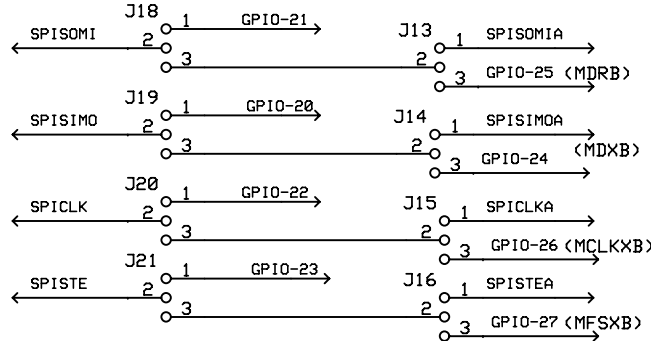
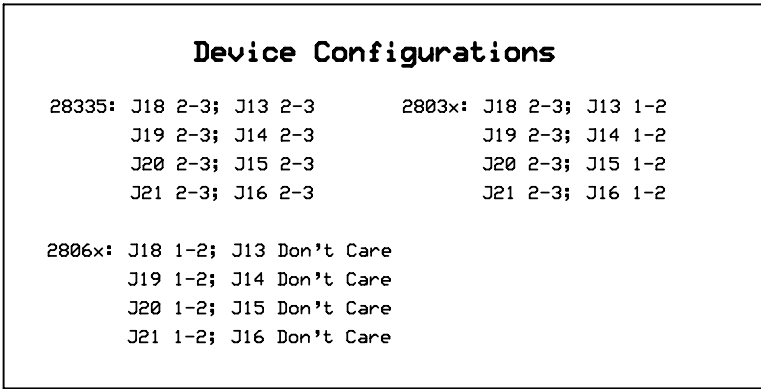
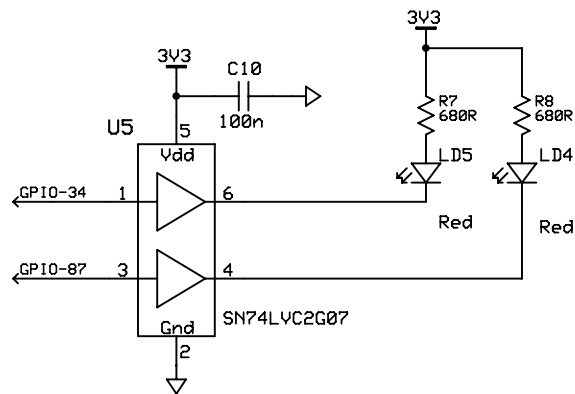
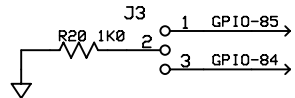
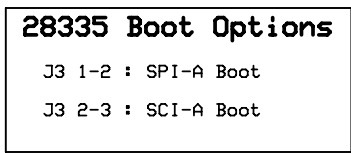
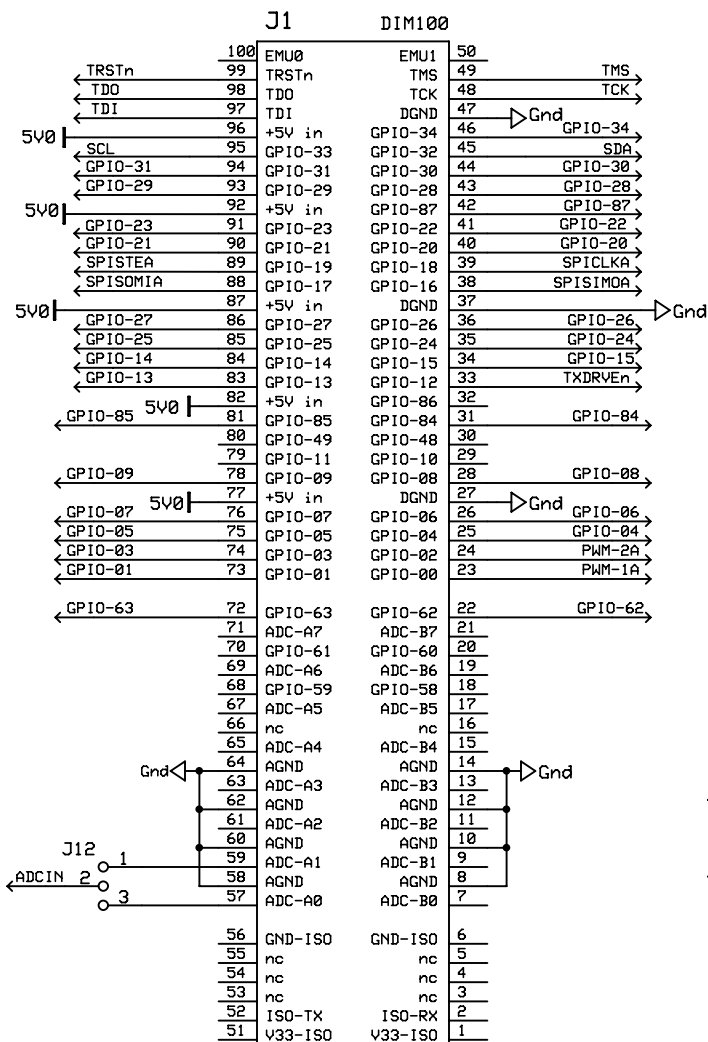
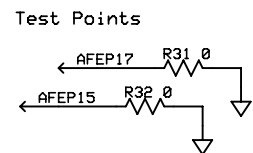
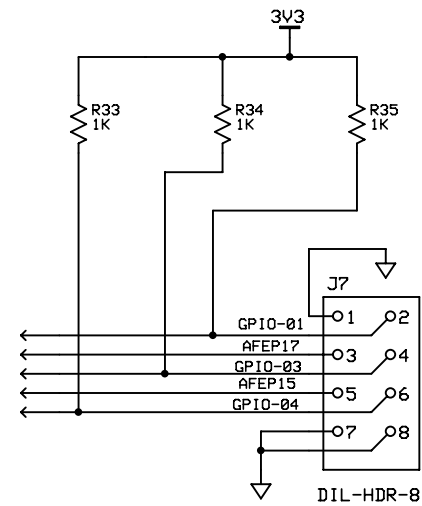
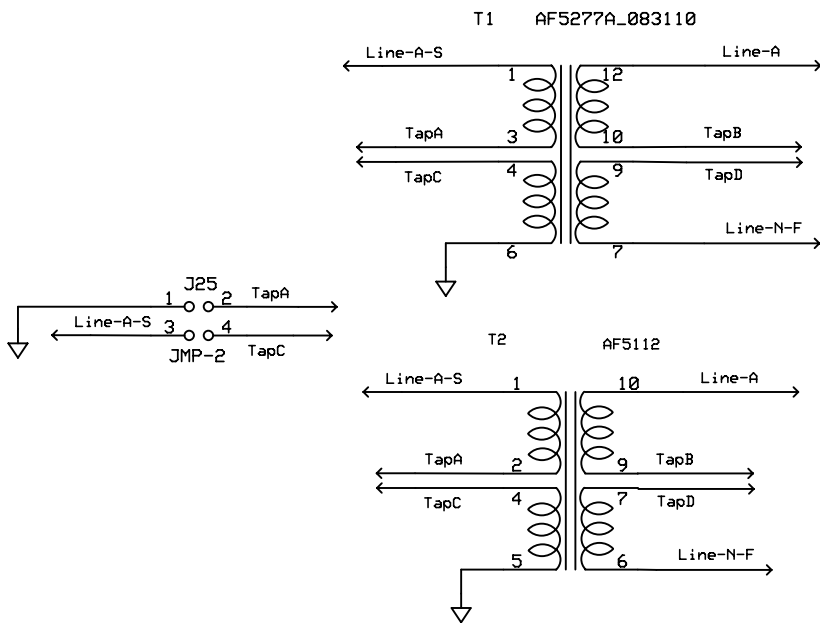
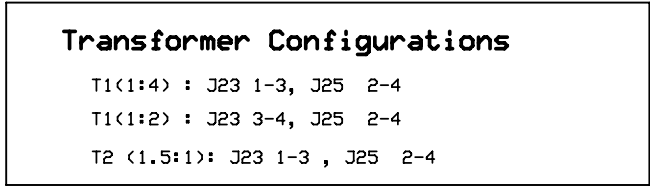
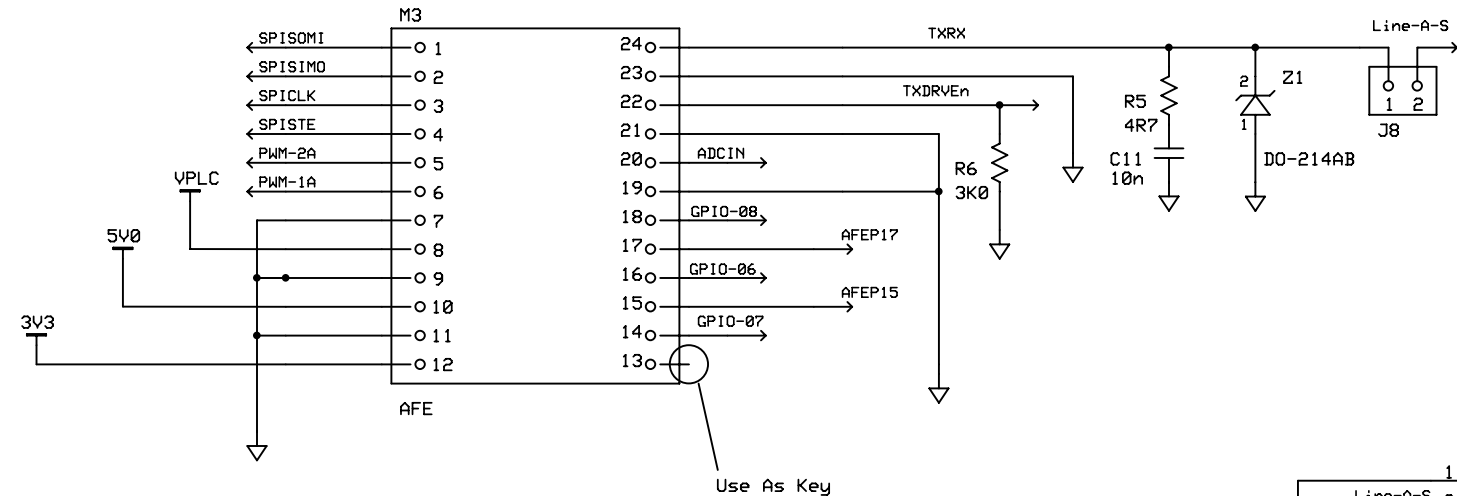
- V3- Release 2 "D-2"
1. Added R28, R28
 2. Added U8, C15, D2
 3. Moved R27, D1
 4. Changed R26, R27 Value
 5. Added J5,J7
 6. Changed J2,J6
 7. Added R31,R32

- V3- Release 3 "D-3"
1. Modified Zero Cross ckt
 2. changed T1
 3. Added PU to GPIOs 1,3,4
 4. Changed J2 to DB9
 5. Modified J6 pinout
 6. Added J10 and J17

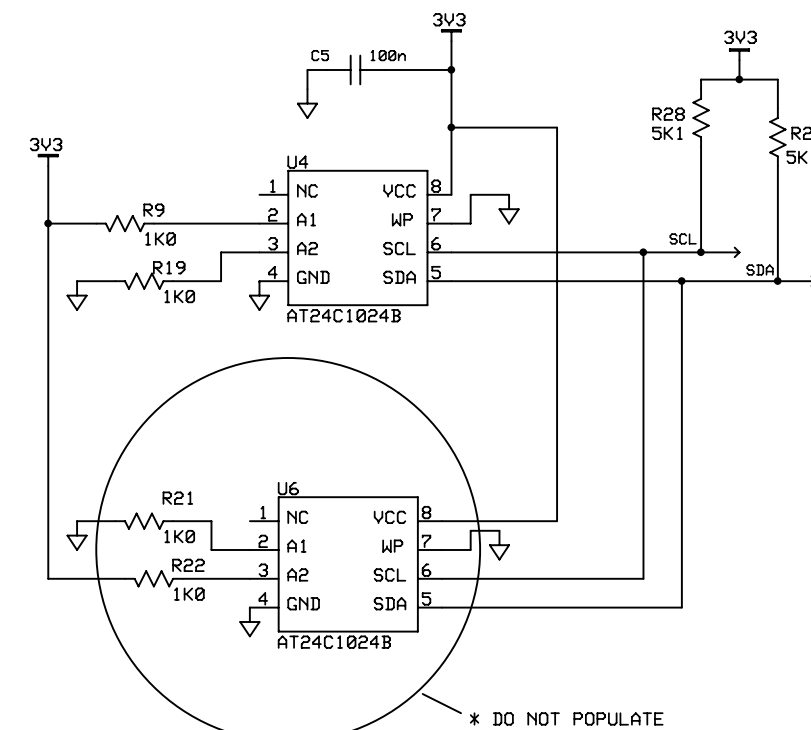
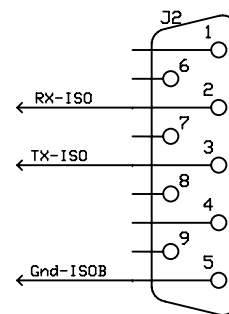
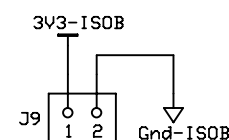
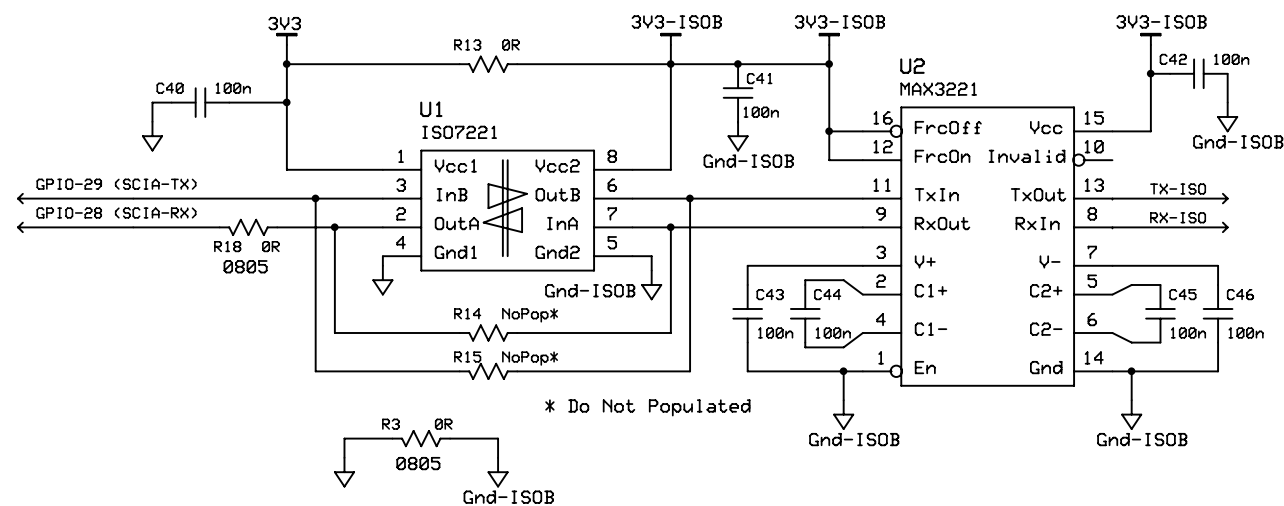
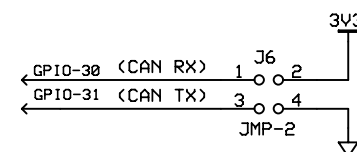
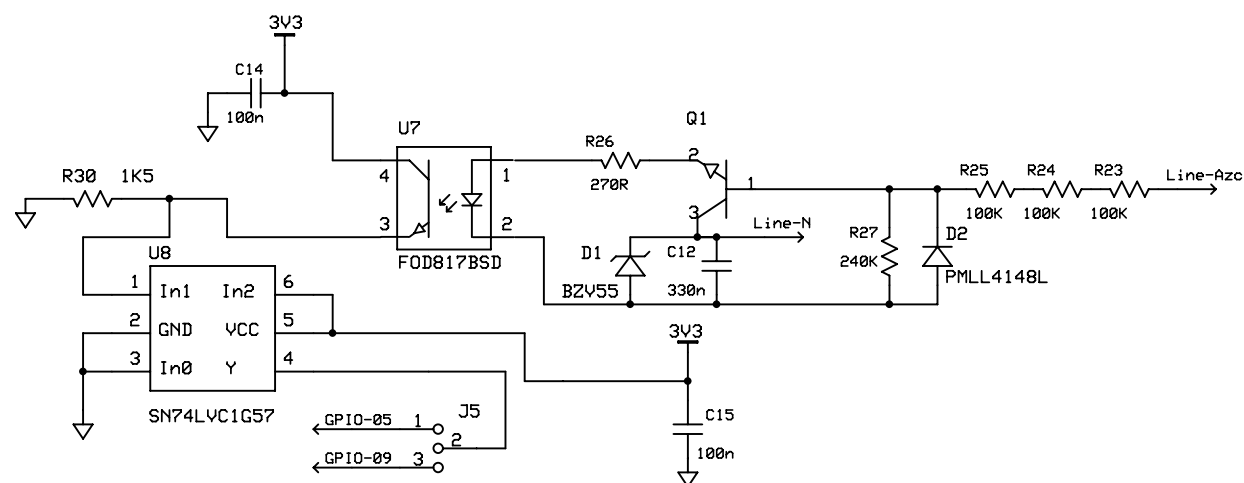
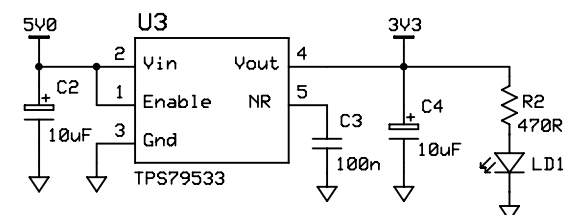
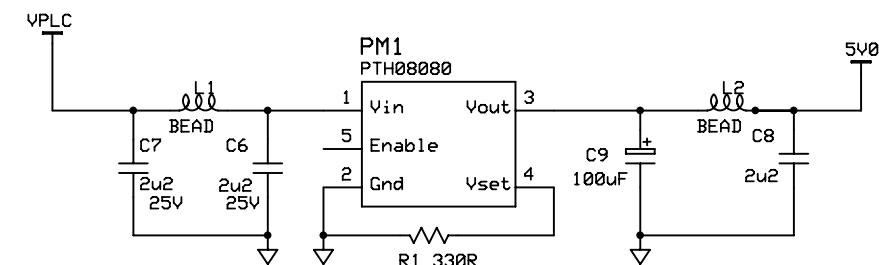
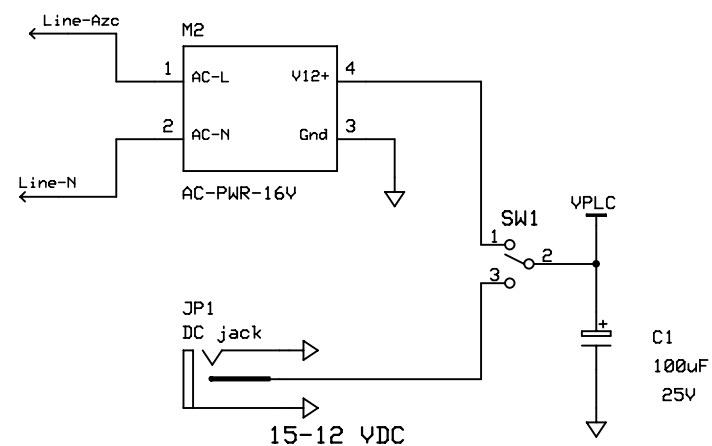
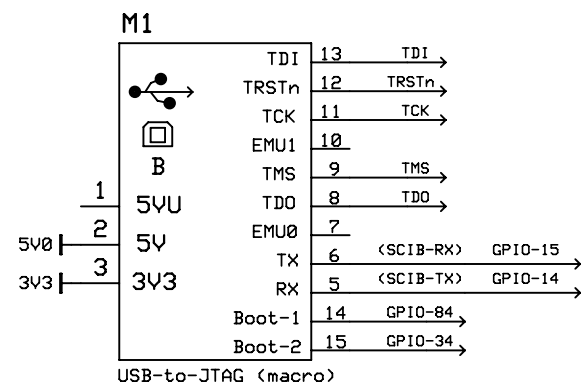
- V3- Release 3 "D-4"
1. Added L5
 2. No Populate for L3, L4
 3. Changed 12V0 to VPLC

- V3- Release 3 "D-5"
1. changed connections to M2

- V3- Release 6 "F-0"
- Added J18-25
Added C16
Added L6
Changed L3, L4
Changed U5
Changed J6,J12
Changed T1
Removed R12,11,12,17
Removed D3,6,7,8
Removed J4,J11
Added CAN Bus GP30,31 to J6
Updated Jumper Information



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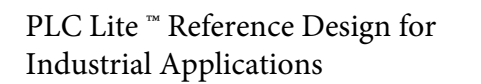
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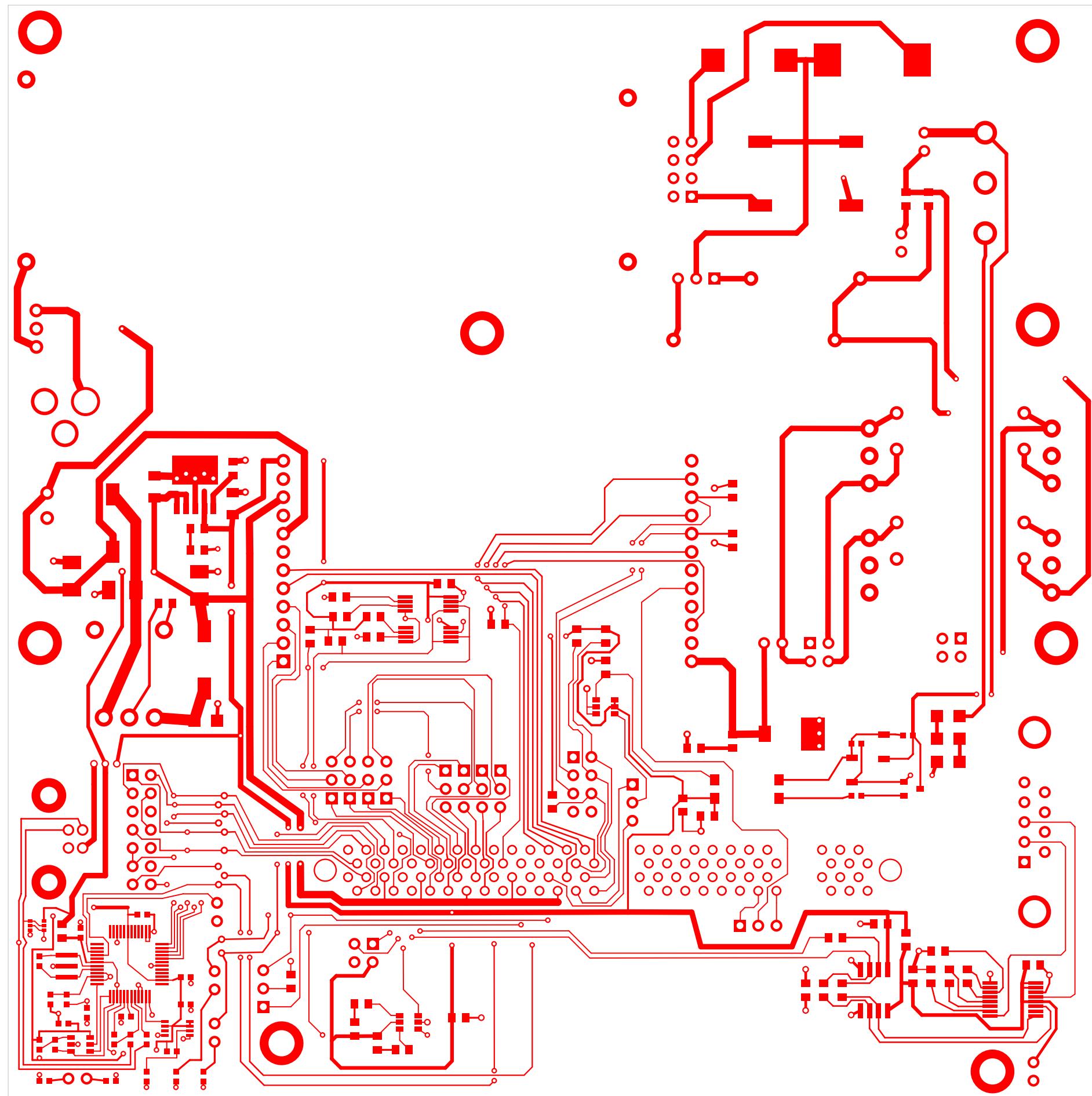
Texas Instruments
PLC-Docking-Station

C2000 - MSW

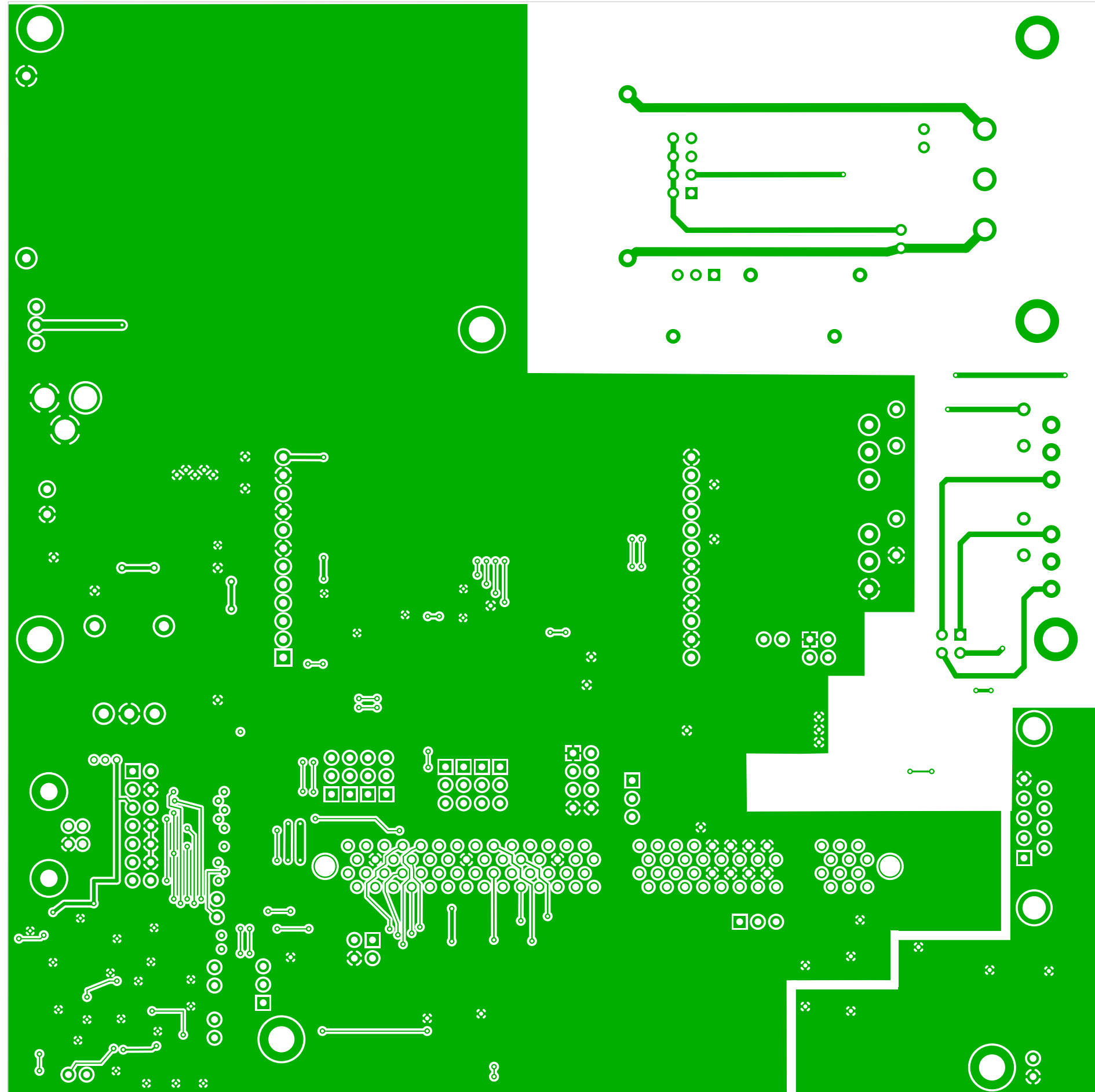
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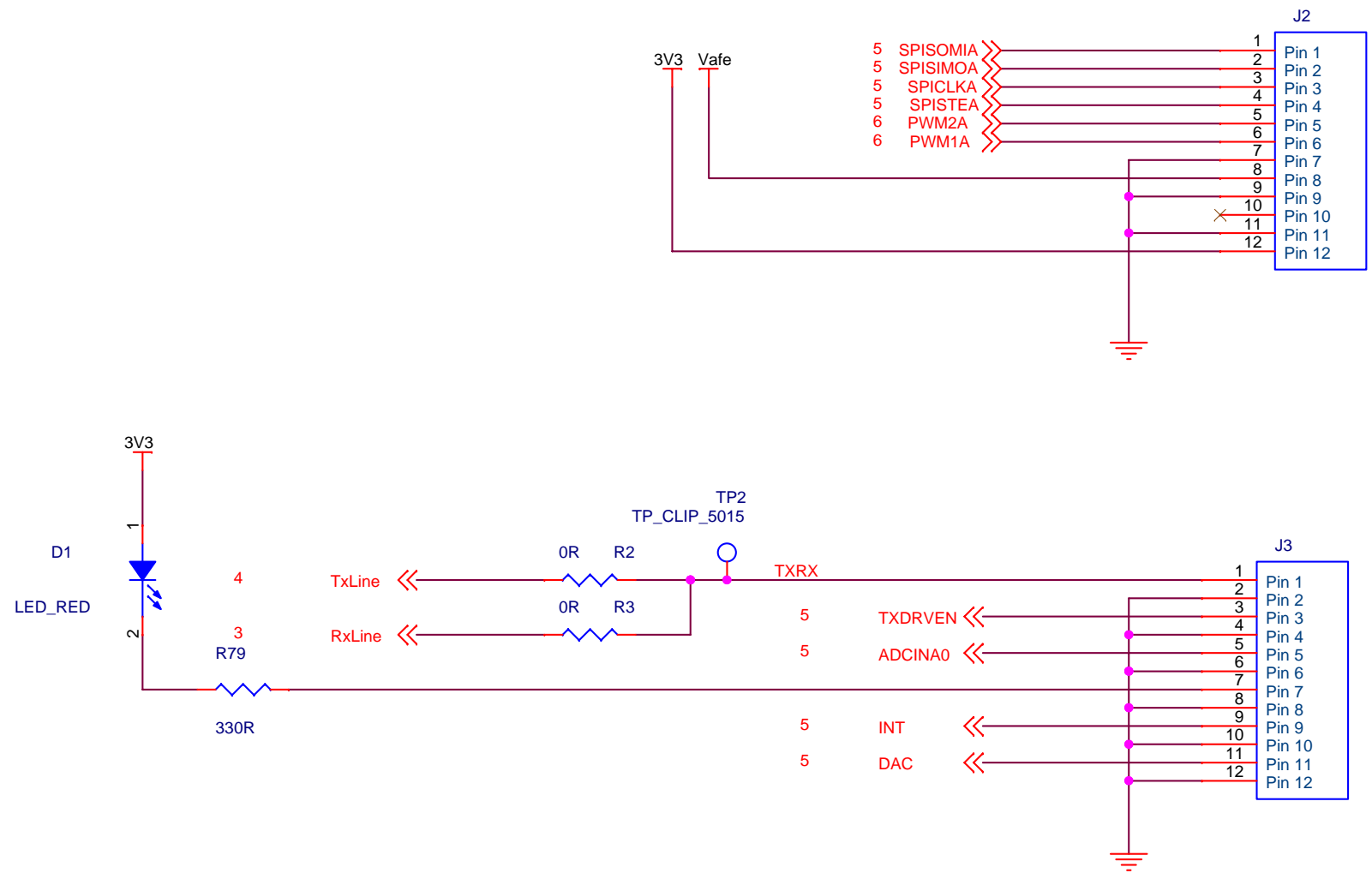


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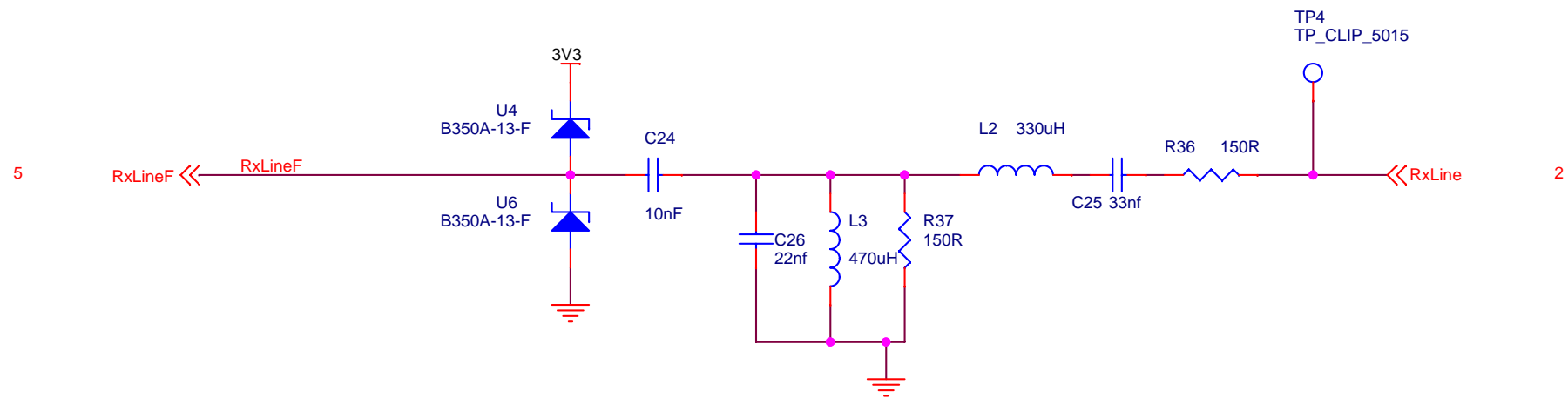
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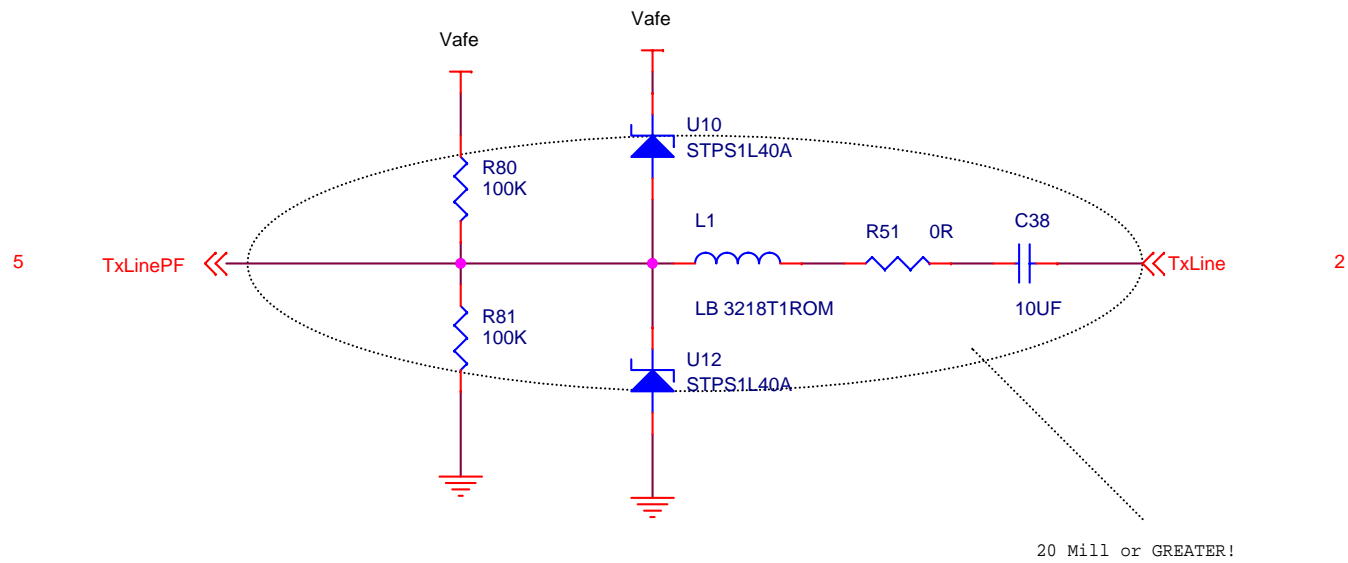
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Date: Thursday, January 06, 2011	Sheet 2 of 6




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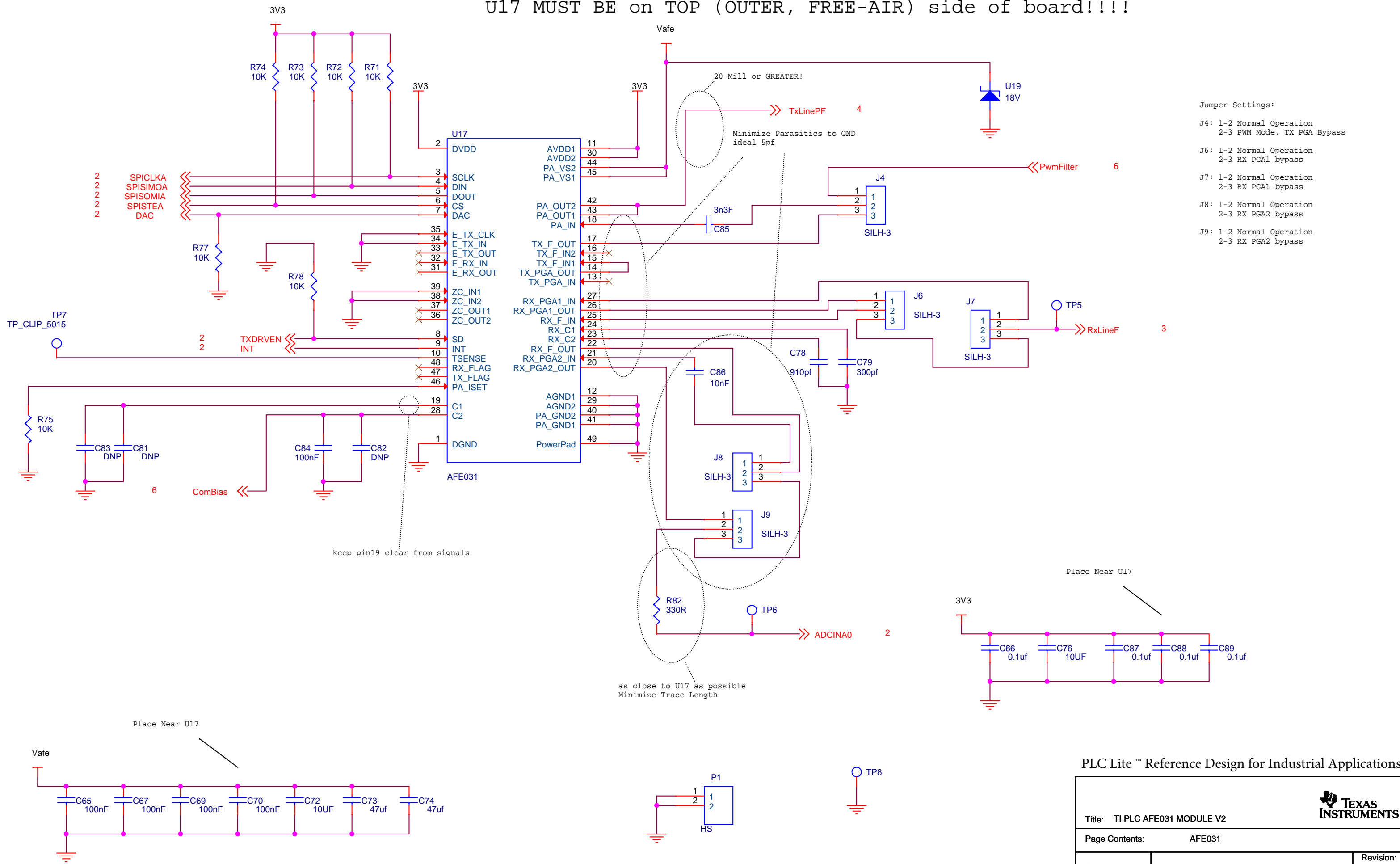
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Page Contents: AFE1 (Passive RX Filter)				
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Date:	Thursday, January 06, 2011		Sheet 3 of	6



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Title: TI PLC AFE031 MODULE V2	
Page Contents: AFE2 (Passive TX filter)	
Size:B	<Doc>
Revision: 0.10	
Date: Thursday, January 06, 2011	Sheet 4 of 6

U17 MUST BE on TOP (OUTER, FREE-AIR) side of board!!!!



- Jumper Settings:
- J4: 1-2 Normal Operation
2-3 PWM Mode, TX PGA Bypass
 - J6: 1-2 Normal Operation
2-3 RX PGA1 bypass
 - J7: 1-2 Normal Operation
2-3 RX PGA1 bypass
 - J8: 1-2 Normal Operation
2-3 RX PGA2 bypass
 - J9: 1-2 Normal Operation
2-3 RX PGA2 bypass

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Page Contents: AFE031				
Size: B	<Doc>		Revision: 0.10	
Date:	Thursday, January 06, 2011		Sheet 5 of 6	

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